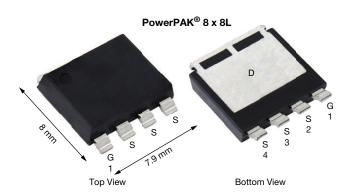


Vishay Siliconix

# Automotive N-Channel 200 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	200			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0143			
I <sub>D</sub> (A) <sup>e</sup>	95			
Configuration	Single			

#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>q</sub> and UIS tested
- Thin 1.6 mm height
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



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N-Channel MOSFET	, S

ORDERING INFORMATION	
Package	PowerPAK® 8 x 8L
Lead (Pb)-free and halogen-free	SQJQ190E (for detailed order number please see <a href="https://www.vishay.com/doc?79776">www.vishay.com/doc?79776</a> )

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V <sub>DS</sub>	200	V
Gate-source voltage	V <sub>GS</sub>	± 20		
Continuous drain current <sup>e</sup>	T <sub>C</sub> = 25 °C		95	
	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	55	
Continuous source current (diode conduction)  Pulsed drain current a, e		I <sub>S</sub>	340	Α
		I <sub>DM</sub>	254	
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	44	
Single pulse avalanche energy	L = 0.1 MH	E <sub>AS</sub>	96	mJ
Maximum power dissipation <sup>e</sup>	T <sub>C</sub> = 25 °C	Б	375	14/
	T <sub>C</sub> = 125 °C	$P_{D}$	125	W
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Soldering recommendations (peak temperature) c			260	1

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient	PCB mount b	$R_{thJA}$	40	°C/W	
Junction-to-case (drain) e		R <sub>thJC</sub>	0.4	G/VV	

#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- b. When mounted on 1" square PCB (FR4 material)
- c. See solder profile (www.vishay.com/doc?73257)
- d. As per JESD51-14
- e. Values based on R<sub>thJC</sub> and T<sub>C</sub> of 25 °C. Actual values achievable will be dependent on the thermal characteristics of the complete system

# Vishay Siliconix

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static					•	•		
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		200	-	-	V	
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	3	3.5	V	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
Zero gate voltage drain current		$V_{GS} = 0 V$	V <sub>DS</sub> = 200 V	-	-	1		
	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 200 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 200 V, T <sub>J</sub> = 175 °C	1	-	1000		
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	$V_{GS} = 10 \text{ V}$	$V_{DS} \ge 5 V$	50	-	-	Α	
Drain-source on-state resistance <sup>a</sup>		$V_{GS} = 10 \text{ V}$	$I_{D} = 20 \text{ A}$	ı	0.0119	0.0143	Ω	
	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}$	I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C	1	-	0.0298		
		$V_{GS} = 10 \text{ V}$	I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C	ı	-	0.0409		
Forward transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		ı	55	-	S	
Dynamic <sup>b</sup>								
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V, f = 1 MHz	-	3187	4800	pF	
Output capacitance	Coss			-	347	550		
Reverse transfer capacitance	C <sub>rss</sub>			-	13	25		
Total gate charge <sup>c</sup>	$Q_g$			1	52	80		
Gate-source charge <sup>c</sup>	$Q_{gs}$	$V_{GS} = 10 \text{ V}$ $V_{DS} = 100 \text{ V}, I_D = 30 \text{ A}$	1	15	-	nC		
Gate-drain charge <sup>c</sup>	$Q_{gd}$				14		-	
Gate resistance	$R_g$	f = 1 MHz		1.8	3.68	5.7	Ω	
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD} = 100 \text{ V}, \text{ R}_L = 3.33 \Omega,$ $I_D \cong 30 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		1	12	20	ns	
Rise time <sup>c</sup>	t <sub>r</sub>			1	6	10		
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>			ı	37	60		
Fall time <sup>c</sup>	t <sub>f</sub>			1	8	15		
Source-Drain Diode Ratings and Charact	teristics <sup>b</sup>							
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	254	Α	
Forward voltage	$V_{SD}$	I <sub>F</sub> = 40 A, V <sub>GS</sub> = 0 V		-	0.81	1.1	V	
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		-	117	234	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>			-	631	1262	nC	
Reverse recovery fall time	t <sub>a</sub>			-	96	-	ns	
Reverse recovery rise time	t <sub>b</sub>			-	21	-		
	1				-10	_	Α	

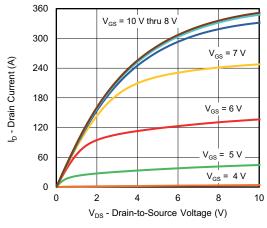
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

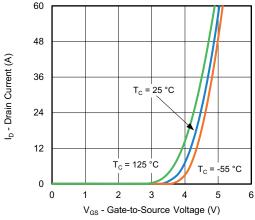
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



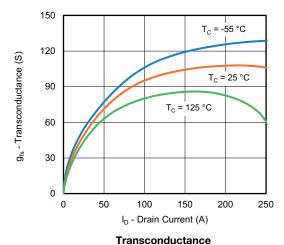
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

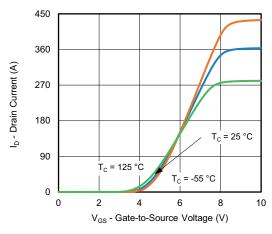


#### **Output Characteristics**

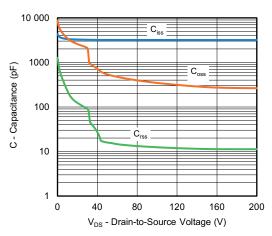


Transfer Characteristics

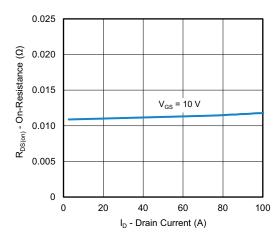




**Transfer Characteristics** 



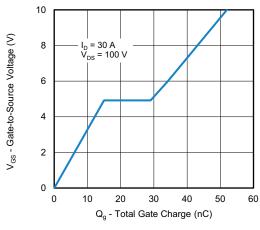
Capacitance



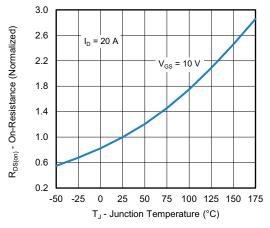
**On-Resistance vs. Drain Current** 



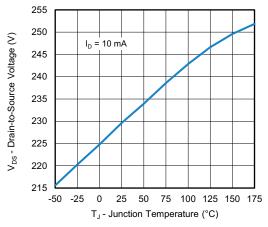
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



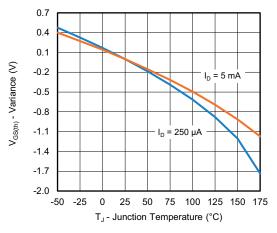
#### **Gate Charge**



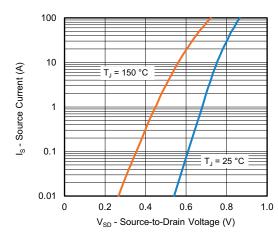
On-Resistance vs. Junction Temperature



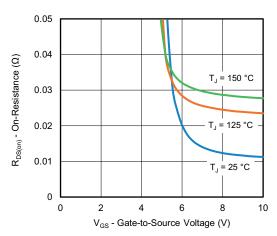
Drain Source Breakdown vs. Junction Temperature



**Threshold Voltage** 



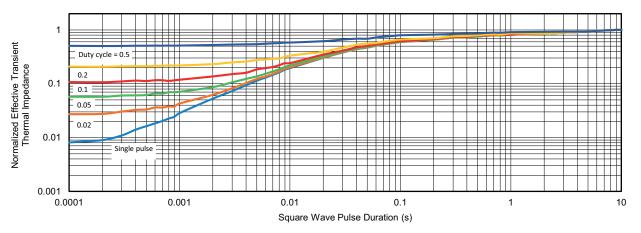
Source Drain Diode Forward Voltage



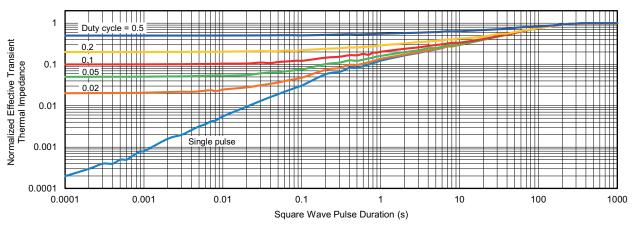
On-Resistance vs. Gate-to-Source Voltage



## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient

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